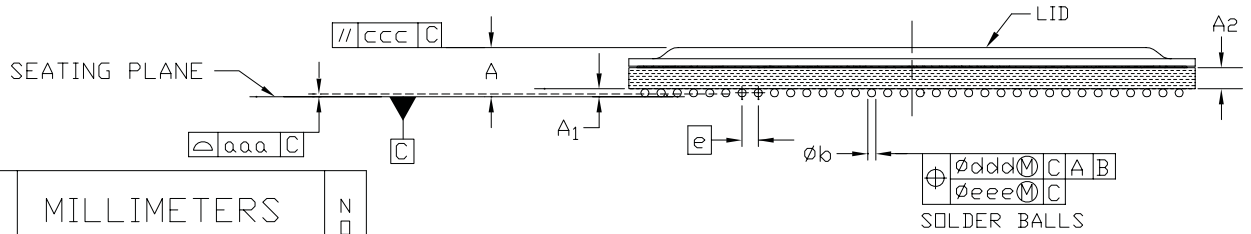
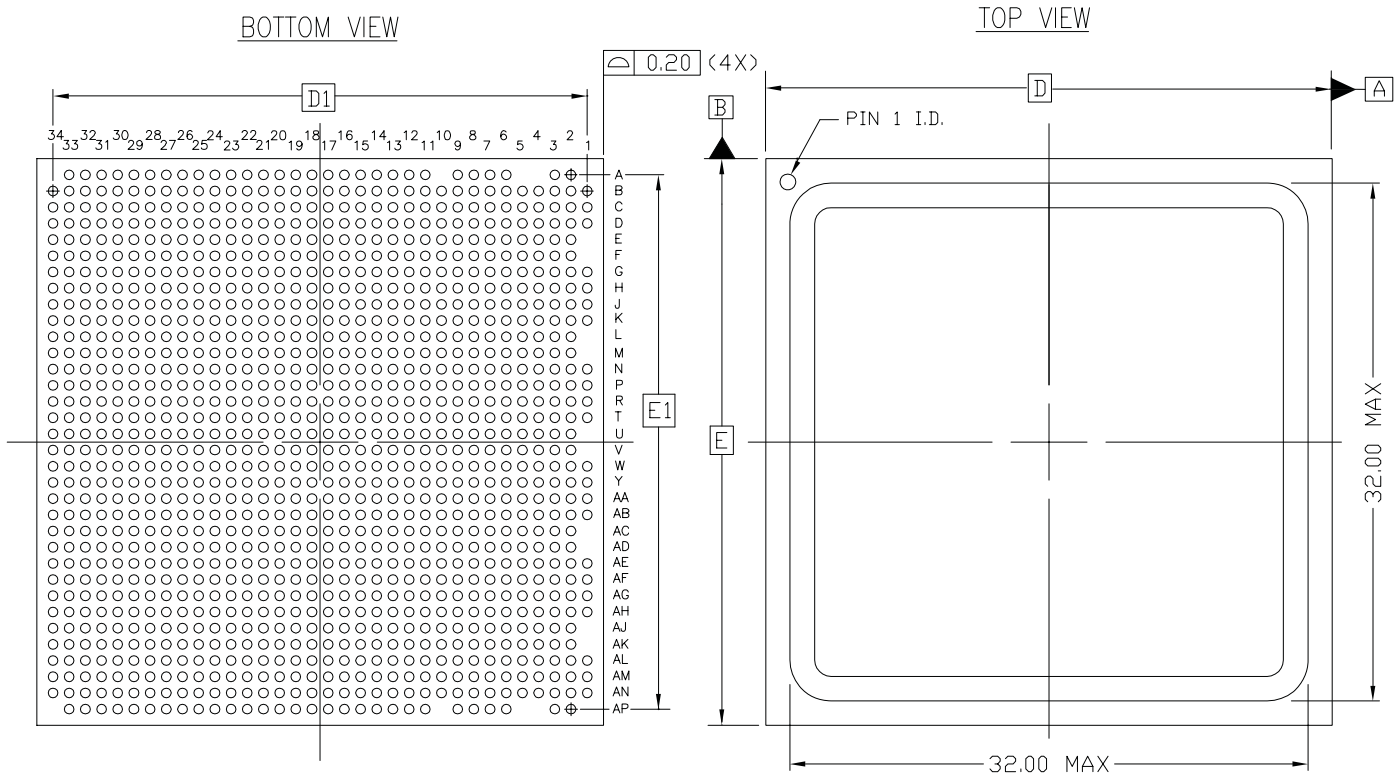


# Flip-Chip BGA (FF1136) Package



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	2.70	<i>~</i>	3.40	2
A <sub>1</sub>	0.40	0.50	0.60	
A <sub>2</sub>	0.90	<i>~</i>	1.40	
D/E	35.00 BASIC			
D <sub>1</sub> /E <sub>1</sub>	33.00 REF			
e	1.00 BASIC			
øb	0.50	0.60	0.70	
aaa	<i>~</i>	<i>~</i>	0.20	
ccc	<i>~</i>	<i>~</i>	0.35	
ddd	<i>~</i>	<i>~</i>	0.30	
eee	<i>~</i>	<i>~</i>	0.10	
M	34			

**NOTES:**

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAR-1 (DEPOPULATED)

**1136 BALL - FLIP-CHIP BGA (FF1136)  
35 X 35mm BODY (1.00mm PITCH)**

## Revision History

The following table shows the revision history for this document.

Date	Version	Revision
3/22/07	1.0	Initial Xilinx release.